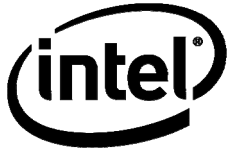


Intel GmbH
Dornacher Strasse 1
85622 Feldkirchen bei München



Press Release

Further information for journalists:

Martin Strobel, Intel GmbH
Phone: +49-(0)89-99143-631
Email: martin.strobel@intel.com

Intel Processors in your Pocket, on the Autobahn, and in the Datacenter

Intel's revolutionary 45nm high-k, metal gate transistor formula makes energy efficient devices possible – ranging from small mobile devices, to desktops, laptops and servers.

CeBIT, Hanover/Feldkirchen, 4th March 2008 – This year, Intel is celebrating its 40th anniversary. A multitude of new Intel processors, based on Intel's 45nm high-k, metal gate semiconductor technology are brought to market. The 45 nanometer manufacturing technology is considered the largest breakthrough in the semiconductor industry since the company was founded.

The theme of this years CeBIT appearance is "IT STARTS WITH THE CHIP". Intel announced the brand names for their new processors and platforms. The new Intel® Atom™ processor is based on Low Power Intel Architecture. These forthcoming tiny and efficient yet powerful processors will be used in Mobile Internet Devices (MIDs), lower-cost laptops and desktop PCs and other CE devices where performance and low power consumption are vital. Furthermore Intel disclosed the Intel® Centrino®2 processor technology for upcoming notebook platforms.

A Low Power Intel Architecture processor will also be available to consumers in a car infotainment system by Harman/Becker in the year 2010. At the same time, Intel announced that its high-end platform for desktop PCs, comprising the Intel® Core™2 Extreme processor QX9770 and the Intel® X48 Express chipset, along with the new Intel® Xeon® LV processors for servers will be launched in March.

The 45nm high-k, metal gate semiconductor technology has once again allowed Intel to double the number of transistors that fit on a chip in comparison to the previous 65nm process. At the same time, Intel has considerably reduced leakage current and further boosted energy efficiency. This required the use of new materials - hafnium in the insulating layer and a metal gate.

Intel Processors in Your Pocket

Processors based on Intel's 45nm high-k, metal gate semiconductor technology consume less power while at the same time providing higher performance: compared with the 65nm process. The new processors reduce power consumption by half thereby keeping the same performance level, or boost performance by up to 38 percent using the same amount of power compared to the previous 65nm process. This will enable increasingly thinner and more stylish mobile devices that also offer longer battery life as the world moves to a more mobile Internet.

Social networking enables people who are physically apart to communicate with each other in a completely new way. Currently performance, energy consumption, compatibility and converging applications, along with non pervasive wireless connectivity and comparatively expensive connections are the limiting factors for internet connectivity on mobile devices. Intel responds to these challenges with its new Intel® Centrino® Atom™ processor technology. Intel's first platform for Mobile Internet Devices (MIDs) will become available in the first half of 2008.

The platform includes the Intel® Atom™ processor, which supports clock speeds of up to 1.86 GHz and an L2 cache size of up to 512 Kbytes, a low power chipset with integrated graphics, and wireless radio designed to enable great battery life, thinner and lighter designs, and an uncompromised internet experience. The processor is about the same size as a one Euro cent coin and consumes less than 2 watts² at full load. MIDs based on the new Intel Centrino Atom processor technology will be available this summer 2008 from Aigo*, Asus*, BenQ*, Clarion*, DiGiFriends*, Gigabyte*, Lenovo*, LG*, Toshiba* and others. Additionally, Panasonic* has announced the release of the first Toughbook* based on the Intel® Atom™ processor.

Intel Processors on the Autobahn

Low Power Intel Architecture (LPIA) will be powering the car Infotainment systems of the future. In cooperation with Harman/Becker* Intel presents the Harman Power Connect (HPC) car infotainment system, which is based on LPIA. Users will profit from standards-based hardware and software that is both flexible and scalable. This will mean faster time to market. On top of this, developers will be

able to implement a variety of HMI (Human Machine Interface) features that support all kinds of digital media and future standards. For example the platform integrates WiFi, WiMax, Bluetooth, 3G, USB, SD/MMC, MOST and a CAN bus connector, while at the same time offering support for popular media players and UPnP (Universal Plug-and-Play) devices. The HPC Car Infotainment System will be available in the year 2010.

40 Years of Intel and 5 Years of Intel® Centrino® Processor Technology

Besides its 40th anniversary, Intel is also celebrating the fifth birthday of the Intel Centrino processor technology. Since the product launch at CeBIT 2003, Intel has continually improved this notebook platform. The next generation will be launched in the second quarter of 2008 under the new name of Intel Centrino 2 processor technology. With the new platform Intel addresses customer requirements for longer battery life, improved performance, and as high-definition video becomes more prevalent than ever the ability to decode high resolution content up to 1080i/p on the chipset further enhances the battery life. The 60 percent smaller package versions will enable manufacturers to innovate smaller and thinner form factors. Business customers in particular will take advantage of the ongoing developments of Intel® Active Management Technology.

Intel Processors for High-End Gaming and Performance Enthusiasts

Intel also demonstrated two new high-end processors for desktop users. The Intel® Core™2 Extreme processor QX9770 offers 12MB L2 cache, a fast 1600 MHz system bus and four cores with a clock speed of 3.2 GHz. In combination with the Intel® X48 Express chipset the new platform achieves groundbreaking results in current benchmark tests and masters even the most challenging tasks. For experienced enthusiasts who desire even more performance, the Intel Core 2 Extreme processor bus ratio locks (overspeed protection) have been removed³. These high-end chips will be available to consumers in March.

Intel Processors in the Server Room

At CeBIT Intel is also exhibiting the Sun Modular Datacenter* - a solar-powered, mobile data center in a standard container. A solar power plant by solar cell manufacturer ersol AG, and the photovoltaic module and system integrators GSS Gebäude-Solarsysteme GmbH and ALTEC Solartechnik supplies the electricity needed to run the data centre. The system's nominal power rating is around 10 Kw_p (Kilo Watt peak). In 2004, this output would not have been sufficient to run a server with a processing power of 5.1 M bops. At the time, a system with this performance required 48kW. A server with Intel® Xeon® 5400 quad core processors consumes just 6kW⁴ at the same performance level. Power consumption could be

reduced even further by using new low voltage Intel Xeon processors featuring a TDP of 50W based on 45nm high-k metal gate semiconductor technology launching later this March. Based on these figures, operations using a similar solar power plant are conceivable today.

Intel, the world's leaders in semiconductor innovation, develops technologies, products and initiatives to continually improve the way people live and work. For more information on Intel visit www.intel.com/pressroom and <http://blogs.intel.com>.

© 2008 Intel Corporation. All rights reserved.

Intel and the Intel logo are trademarks of Intel Corporation in the United States and other countries.

* Other names and brands may be claimed as the property of others.

**45nm product is manufactured on a lead-free process. Lead-free per EU RoHS directive July 2006. Some E.U. RoHS exemptions may apply to other components used in the product package.

***Residual amounts of halogens are below November 2007 proposed IPC/JEDEC J-STD-709 standards.

² Thermal Design Power (TDP) consumption is measured at 2W using a synthetic power-virus test at a frequency of 2GHz.

³ Altering clock frequency and/or voltage may (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications

⁴ Performance comparison using SPECjbb2005 bops (business operations per second) between (2004) 2 socket single core Intel Xeon processor (3.6GHz) and (2008) 2 socket Quad-Core Intel Xeon processor E5450 (3.0GHz, 80W, 1333MHz) measured 8/22/07. 1 Floor space based foot on sq ft reduction. 2 Energy costs based on total solution rack power. 3 Energy Savings based on an electric rate of \$0.10/kWh assuming 33% average server load. 4 ROI is calculated based on cost of new servers (\$6,264 per server pricing based on HP DL 380G5 (32GB RAM) as of Nov 17, 2007. source www.hp.com) divided by energy savings per year. Actual performance results and savings may vary depending on configuration. See backup for details.

⁵ Performance tests and ratings are measured using specific computer systems and/or components and reflect the approximate performance of Intel products as measured by those tests. Any difference in system hardware or software design or configuration may affect actual performance. Buyers should consult other sources of information to evaluate the performance of systems or components they are considering purchasing. For more information on performance tests and on the performance of Intel products, visit <http://www.intel.com/performance/resources/limits.htm>.